

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner of Patents, Alexandria, Virginia, 22313-1450 on December 12, 2003.

Rosalie A. Centeno Secretary

In the Application of Rolf Hertling et al

Ser.No.:

09/831,842

Filed:

May 11, 2001

For:

METHOD FOR DETERMINING THE THICKNESS OF A MULTI-THIN-

LAYER STRUCTURE

Commissioner of Patents

Alexandria, Virginia 22313-1450

INFORMATION DISCLOSURE STATEMENT

In accordance with 37 CFR § 1.56, Applicant wishes to call the attention of the Examiner to the following references:

1) JP 2000-310512

Reference 1, JP2000310512, discloses the following:

PROBLEM TO BE SOLVED: To accurately measure the film thickness and the distribution of film thickness without influence of a base pattern by optically obtaining a film thickness of a transparent film according to the frequency and phase of spectral waveform of a detected reflection light.

SOLUTION: A light reflected on a wafer passes through an iris focus 10 and a lens 9, and its optical path is changed through a beam splitter 8 and enters a diffraction grating

11, A light splitted spectrally by the diffraction grating 11 is formed on a detector 12, and its spectral intensity distribution 15 can be obtained. The reflection light produces an interference due to a film to be measured, and it has a distribution of spectral intensity corresponding to the structure within a film. The distribution of spectral intensity is subjected to film-thickness calculation processing such as correction and frequency analysis, etc., so as to obtain a film thickness. A light source having a wide wavelength band range such as a tungsten halogen lamp, a xenon lamp, etc., is perferably used as a white light source 6. A laser light with a plurality of different wavelengths may be also used. A CCD two-dimensional sensor or a one- dimensional line sensor may be used as a detector 12.

A copy of the listed document is submitted herewith along with the form PTO-1449.

It is respectfully requested that any fees required and not enclosed herewith or any shortages in any fees be charged to Deposit Account 02-1653.

Consideration of the foregoing in relation to this application is respectfully requested.

Respectfully submitted,

Robert - Becker Robert W. Becker, Reg. No. 26,255

for the Applicants

Robert W. Becker & Associates

707 Hwy 66 East, Suite B

Tijeras, NM 87059

Telephone: (505) 286-3511

Telefax: (505) 286-3524

RWB/rac Enclosures

Ç

1

OIPE JO	.)
DEC 1 8 2003	A HOLE
The The The Present	Z IN

INFORMATION DISCLOSURE STATEMENT BY APPLICANT	Compl t if Known		
	Application Number	09/831,842	
	Filing Date	May 11, 2001	
	First Named Inventor	Rolf Hertling	
	Group Art Unit		
	Examiner Name		
	Attorney Docket No.	AZ.2657	

	U. S. PATENT DOCUMENTS						
Examiner Initials	Cite No.	Patent Number Pub. Number	Issue Date Pub. Date	Patentee	Class	Subclass	Filing Date
•					Y		

FOREIGN PATENT DOCUMENTS								
Examiner Initials	Cite No.	Document Number	Publication Date	Country or Patent Office	Class	Subclass	Trans	lation
	ļ						Vac	Ma
	1	JP2000310512	07 Nov 2000	Japan			Х	
	<u> </u>							
			†			\	 	
	 		<u> </u>					
	+					 		

OTHER PRIOR ART B NON PATENT LITERATURE DOCUMENTS					
Examiner	Cite				
Initials	No.				

Examiner	Date	

12/12/2003